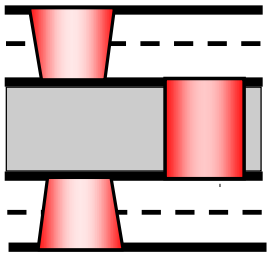
Build Up HDI (Standard)

HDI04_1+2b+1_0,90_engl

4 - Layers
Core: 0,71 mm Cu 35/35 µm

WE-Articel No.:	**1 + 2B + 1**
Customer:	

WÜRTH ELEKTRONIK

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	**12**	
					1 x 1080	**60**	
	2			12 µm		**35**	
			0,710 mm			**710**	
	3			12 µm		**35**	
					1 x 1080	**60**	
	BOT/RS		Foil	12 µm	1)	**12**	

1) copper thickness outer layers: appr. 55 µm

						total material thickness:		924	

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**0,90**	+/-	0,08	mm			Date:	Engineer:
thickness with electro plated Cu:	0,99	+/-	0,11	mm				
total thickness with soldermask	1,05	+/-	0,13	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision		
04.01.2006	**S. Keller**	04.05.2006	M.Kress	04.01.2006	R. Schönholz	00	page:	7+